

<b>INFORMATION DISCLOSURE CITATION</b> <small>(Use several sheets if necessary)</small>				ATTY DOCKET NO. <b>BUR9-000-0075-US1</b>		SERIAL NO. <b>U.S. 684463</b>	
				<b>Timothy H. Daubenspeck et al.</b>		<b>FILING</b> <b>GROUP</b>	
<b>U.S. PATENT DOCUMENTS</b>							
<b>EXAMINER INITIAL</b>	<b>DOCUMENT NUMBER</b>	<b>DATE</b>	<b>NAME</b>	<b>CLASS</b>	<b>SUBCLASS</b>	<b>FILING DATE IF APPROPRIATE</b>	
<i>A.S.</i>	<b>5,659,201</b>	<b>8/1997</b>	<b>Wollesen</b>				
	<b>5,447,887</b>	<b>9/1995</b>	<b>Filipiak et al.</b>				
	<b>5,273,920</b>	<b>12/1993</b>	<b>Kwasnick et al.</b>				
<i>↓</i>	<b>4,198,744</b>	<b>4/1980</b>	<b>Nicolay</b>				
<b>FOREIGN PATENT DOCUMENTS</b>							
<b>DOCUMENT NUMBER</b>	<b>DATE</b>	<b>COUNTRY</b>	<b>CLASS</b>	<b>SUBCLASS</b>	<b>TRANSLATION</b>		
					<b>YES</b>	<b>NO</b>	
<b>OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
<i>A.S.</i>	<b>IBM Technical Disclosure Bulletin, Vol. 32, No. 3A, August 1989, FUSE STRUCTURE FOR WIDE FUSE MATERIALS CHOICE, pages 438-439</b>						
<i>A.S.</i>	<b>SILICON NITRIDE COATINGS ON COPPER, Audisio et al., Vol. 119, No. 4, April 1972, Electrochemical Society, pages 408-411</b>						
<b>EXAMINER</b>				<b>DATE CONSIDERED</b>			

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.